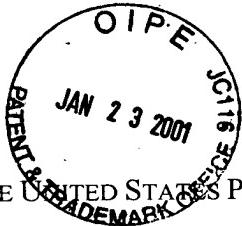


X3 GP 3729



Patent
Docket No.: 53434USA8C.009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Peter B. Hogerton et al.

Serial No.: 09/690,600
Filed: October 17, 2000
For: SOLVENT ASSISTED BURNISHING
OF PRE-UNDERFILLED SOLDER-
BUMPED WAFERS FOR FLIPCHIP
BONDING

Group Art Unit: 3729

Examiner:

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INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Pursuant to 37 C.F.R. 1.97 and 1.98, enclosed please find a completed form PTO-1449 citing references submitted for consideration during examination of the above-referenced patent application. A copy of each of the references cited therein is also enclosed.

It is respectfully requested that the Examiner initial and return the enclosed Form PTO-1449 in order to indicate that each of the references listed thereon has been considered in connection with the present application.

Respectfully submitted,

Matthew B. McNutt
Registration No. 39,766

Date: JAN 18, 2001
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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on:

1-18-01

Signed:

Tom Sanders